

Ceramic RF Devices

PRECAUTIONS

1. PCB Design

◆ Land pattern design

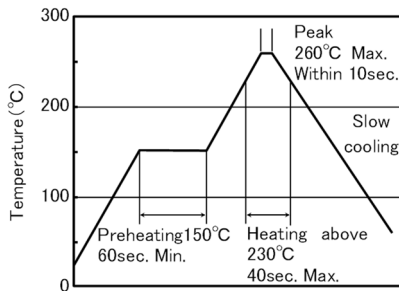
Land pattern dimension examples

Technical considerations	TSD1M15H/TSL1N15H LGA 6Pins type	TSB1N15H/TSL1N15H Side 4Pins type	TSB1N18F Side 4Pins type	TSB1N18D/TSL1N18D /TSH1N18D LGA 3Pins type
	Unit: mm	Unit: mm	Unit: mm	Unit: mm
	TSD1N18B LGA 6Pins type	TSD1N18D/TSL1N18D /TSC1N18D Side 6Pins type	TSC4N18F Side 8Pins type	TSB1N21D LGA 3Pins type
	Unit: mm	Unit: mm	Unit: mm	Unit: mm
	TSD1N21A829MLS0G2T /TSD1N21C LGA 6Pins type	TSD1N21 LGA 6Pins type	TST1N22D LGA 9Pins type	
Unit: mm	Unit: mm	Unit: mm		

2. Soldering

◆ Conditions for Reflow soldering (for reference)

• Pb Free Reflow Profile



- ※ Components should be preheated to within 100 to 130°C from soldering temperature.
- ※ Assured to be reflow soldering for 2 times.

Note : The above profiles are the maximum allowable soldering condition, therefore these profiles are not always recommended.

3. Storage conditions

Precautions

◆ Storage conditions

1. The Products must not be used in the following environments :

- exposure to special gases such as (C12, NH3, SOx, NOx)
- exposure to volatile gas or inflammable gas
- exposure to a lot of dust
- exposure to water or condensation
- exposure to direct sunlight or freezing

2. The Products should be kept in the following conditions :

- Temperature : $-10\sim +40^{\circ}\text{C}$
- Humidity : 15~85%RH max.

3. The products should be used within 6 months after delivery. In case of storage over 6 months, solderability shall be checked before actual usage.

■ Please contact of our offices for further details of specifications.

All of the standard values listed here are subject to change without notice.

Therefore, please check the specifications carefully before use.